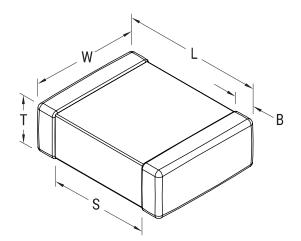




SMD Comm X8G HT150C Flex, Ceramic, 750 pF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

100 GOhms

	Specifications	
2	Capacitance	750 pF
mm +/-0.4mm	Measurement Condition	1 MHz 1.0Vrms
mm +/-0.3mm	Tolerance	5%
m +/-0.10mm	Voltage DC	250 VDC
mm MIN	Dielectric Withstanding Voltage	625 VDC
mm +/-0.35mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
R, 330mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
00	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Insulation Resistance

 Chip Size
 1812

 L
 4.5mm +/-0.4mm

 W
 3.2mm +/-0.3mm

 T
 1mm +/-0.10mm

 S
 2.3mm MIN

 B
 0.7mm +/-0.35mm

Packaging Specifications Packaging T&R

Dimensions

rackaging	ran, ssonnin, ridste rape	
Packaging Quantity	4000	

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